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APPLICATION NO.	I	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/721,110	-	11/24/2003	Chad A. Cobbley	2269-3437.9US (97-0514.09	6106	
24247	7590	02/01/2005		EXAMINER		
TRASK BRITT				KOBERT, RUS	KOBERT, RUSSELL MARC	
P.O. BOX	2550					
SALT LAK	E CITY,	UT 84110		ART UNIT	PAPER NUMBER	
	·			2829		
				DATE MAIL ED. 02/01/200	5	

Please find below and/or attached an Office communication concerning this application or proceeding.

			(<i>G</i> M)				
	Application No.	Applicant(s)					
	10/721,110	COBBLEY ET AL.					
Office Action Summary	Examiner	Art Unit					
	Russell M Kobert	2829					
The MAILING DATE of this communication appeariod for Reply	pears on the cover sheet with th	he correspondence addi	ess				
A SHORTENED STATUTORY PERIOD FOR REPL THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.1 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a rep If NO period for reply is specified above, the maximum statutory period - Failure to reply within the set or extended period for reply will, by statute Any reply received by the Office later than three months after the mailin earned patent term adjustment. See 37 CFR 1.704(b).	136(a). In no event, however, may a reply by the statutory minimum of thirty (30) will apply and will expire SIX (6) MONTHS are, cause the application to become ABANDO	timely filed days will be considered timely. from the mailing date of this com ONED (35 U.S.C. § 133).	munication.				
Status							
1) Responsive to communication(s) filed on 10 E							
·=	s action is non-final.		a a vita i a				
·	ince this application is in condition for allowance except for formal matters, prosecution as to the merits is osed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.						
Disposition of Claims							
 4) ☐ Claim(s) 1.2 and 13-18 is/are pending in the a 4a) Of the above claim(s) 3-12 is/are withdraw 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1.2 and 13-18 is/are rejected. 	• •						
7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/o	or election requirement.						
Application Papers							
9) The specification is objected to by the Examine 10) The drawing(s) filed on 12-10-2004 & 11-24-20 Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Examine	2003 is/are: a) \square accepted or by drawing(s) be held in abeyance. tion is required if the drawing(s) is	See 37 CFR 1.85(a). sobjected to. See 37 CFR	1.121(d).				
Priority under 35 U.S.C. § 119							
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority application from the International Burea	ts have been received. ts have been received in Applicative documents have been received.	cation No	tage				
* See the attached detailed Office action for a list	of the certified copies not rece	eived.					
Attachment(s)							
Notice of References Cited (PTO-892) Notice of Draftsperson's Patent Drawing Review (PTO-948) Notice of Draftsperson's Patent Drawing Review (PTO-948) Notice of Draftsperson's Patent Drawing Review (PTO-948) Notice of References Cited (PTO-949) Notice of References Cited (PTO-892) Notice of References Cited (PTO-948) Notice of Re	4) Interview Summ Paper No(s)/Ma 5) Notice of Inform 6) Other:		52)				

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Art Unit: 2829

1. Applicant's arguments with respect to claims 1, 2, 13-18 have been considered

but are moot in view of the new ground(s) of rejection.

2. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all

obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the

invention was made to a person having ordinary skill in the art to which said subject matter pertains.

Patentability shall not be negatived by the manner in which the invention was made.

3. This application currently names joint inventors. In considering patentability of

the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of

the various claims was commonly owned at the time any inventions covered therein

were made absent any evidence to the contrary. Applicant is advised of the obligation

under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was

not commonly owned at the time a later invention was made in order for the examiner to

consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g)

prior art under 35 U.S.C. 103(a).

4. Claims 1, 2, 13 and 16-18 are rejected under 35 U.S.C. 103(a) as being

unpatentable over Hembree et al in view of Debenham (5764650).

Hembree et al anticipates a method for electrically testing a flip-chip

semiconductor assembly formed from at least one integrated circuit (IC) die (24) and a

substrate (14), the method comprising:

Contacting the substrate with probes (26);

While the substrate is in contact with the probes, bringing the at least one die and the substrate together (via metal clips 34) in conductive contact to form the flip-chip semiconductor assembly; and

Before the at least one die is sealed, electrically testing the assembly using the probes (col 5, ln 19-47); as recited in claim 1.

Although Hembree et al does not show directly *detachably contacting* a surface of the substrate with probes, Debenham shows a method of detachably contacting a surface of a substrate with probes (col 3, ln 38-47 and col 6, ln 66 - col 7, ln 10).

As to claim 2, having a die-attach station is anticipated by Hembree et al (all of Figure 1 is considered a die-attach station).

As to claim 13, having the bond pads on a surface of the die in a cur<u>able</u> conductive contact with conductive pads on the surface of the substrate is considered inherent to Hembree et al.

As to claim 16, the act of bringing the at least one IC die and the substrate together comprises flip-chip attaching (col 4, In 65-67; col 5, In 48-51) the at least one IC die to the substrate is anticipated by Hembree et al.

As to claim 17, reworking the flip-chip semiconductor assembly and retesting the flip-chip semiconductor assembly if the flip-chip semiconductor assembly fails the electrical testing act is anticipated by Hembree et al (Hembree et al discusses "re-work"; see col 1, In 62-68).

As to claim 18, curing the curable conductive contact if the flip-chip semiconductor assembly passes the electrical testing act is considered inherent to Hembree et al (Hembree et al discusses "packaging" only known good die that can only be accomplished in the alternative to "poor wire bonds, cracked packages and improper die attachments"; see col 5, In 31-40)

It would have been obvious at the time the invention was made to have combined the teaching of Debenham with that of Hembree et al to make the claimed invention because Debenham provides an improved method, such as using a handler or prober for contacting pads on a semiconductor device such as a chip on a wafer (see col 3, In 39-65) that is also tested in the Hembree et al patent.

5. Claims 14 and 15 are rejected under 35 U.S.C. 103(a) as being unpatentable over Hembree et al in view of Debenham as applied to claim 1 above, and further in view of Carson et al (5701233).

Although Hembree et al in view of Debenham fail to show the flip-chip semiconductor device having conductive epoxy dots on one of the bond pads on the at least one IC die and the conductive pads on the substrate, Carson et al shows the use of epoxy dots (Figures 14a and 14b) on one of the bond pads on the at least one IC die and the conductive pads on the substrate (col 10, ln 52-62), as mentioned in claim 14. Moreover, Carson et al further emphasizes flip-chip bonding (col 7, ln 35-38) as also mentioned in claim 1.

As to claim 15, the use of conductive epoxy dots being one of wet or dry type is considered inherent to any conductive epoxy dot because the epoxy dots can only be made of a wet or dry type composition.

It would have been obvious to one having ordinary skill in the art at the time the invention was made to have combined the teaching of Carson et al with that of Hembree et al in view of Debenham to make the claimed invention because the assemblies taught by Carson et al provide several advantages over presently available circuit designs such as reliable construction of high-density, complex, high speed circuits with all ancillary supporting circuitry without limiting chip selection, ease of component testing and in-field repairability (col 3, ln 59 - col 4, ln 48).

6. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of

the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Russell Kobert whose telephone number is (571) 272-1963.

The Examiner's Supervisor, Nestor R. Ramirez, can be reached at (571) 272-2034.

For an automated menu of Tech Center 2800 phone numbers call (571) 272-2800.

Russell M. Kobert Patent Examiner Group Art Unit 2829 January 25, 2005

VINH NGUYEN'
PRIMARY EXAMINER
A. U. 2829
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